AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A fluorine containing elastomer composition for a seal material of a semiconductor production device comprising a fluorine containing elastomer and a compound having plasma antiaging effects.

wherein said compound having plasma antiaging effects is at least one selected from the group consisting of an isoindolinone pigment, a quinacridone pigment, a diketopyrrolopyrrole pigment and an anthraquinone pigment.

- 2. (canceled).
- 3. (original): The fluorine containing elastomer composition of Claim 1, wherein said fluorine containing elastomer is a perfluoro elastomer.
 - 4. (canceled).
- 5. (original): The fluorine containing elastomer composition of Claim 1, wherein said compound having plasma antiaging effects is a compound containing no metallic atom.
- 6. (original): The fluorine containing elastomer composition of Claim 1, wherein at least 0.5 part by weight of said compound having plasma antiaging effects is contained based on 100 parts by weight of the fluorine containing elastomer.
- 7. (original): The fluorine containing elastomer composition for the seal material of the semiconductor production device for plasma process of Claim 1.

- 8. (original): The seal material for the semiconductor production device comprising the fluorine containing elastomer composition of Claim 1.
- 9. (original): The seal material for the semiconductor production device for plasma process comprising the fluorine containing elastomer composition of Claim 1.
 - 10. (canceled).
 - 11. (canceled).
 - 12. (canceled).
 - 13. (canceled).
 - 14. (canceled).
 - 15. (canceled).
 - 16. (canceled).
 - 17. (canceled).
- 18. (new): A fluorine containing elastomer composition for a seal material of a semiconductor production device comprising a fluorine containing elastomer and a compound having plasma antiaging effects,

wherein said compound having plasma antiaging effects is an aromatic compound and said aromatic compound is a compound satisfying at least one condition selected from the group consisting of:

- (1) –NH– composes one portion of the ring structure of the aromatic compound, or one side of –NH– is directly bonded with the ring structure of the aromatic compound;
- (2) –C(O)– composes one portion of the ring structure of the aromatic compound;

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- (3) –S– is directly bonded with the ring structure of the aromatic compound;
- (4) –OH is directly bonded with the ring structure of the aromatic compound; and
- (5) at least one side of (-O-)₃P is directly bonded with the ring structure of the aromatic compound.